



## Material Content Data Sheet



<b>Sales Product Name</b>		BTN8962TA		<b>Issued</b>		31. July 2018		
<b>MA#</b>		MA002172702						
<b>Package</b>		PG-TO263-7-1		<b>Weight*</b>		1531.68 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	3.697	0.24	0.24	2414	2414
chip_2	inorganic material	silicon	7440-21-3	1.162	0.08	0.08	758	758
chip_3	inorganic material	silicon	7440-21-3	1.212	0.08	0.08	791	791
leadframe	inorganic material	phosphorus	7723-14-0	0.243	0.02		159	
	non noble metal	iron	7439-89-6	0.810	0.05		529	
wire	non noble metal	copper	7440-50-8	808.613	52.80	52.87	527926	528614
	non noble metal	aluminium	7429-90-5	2.741	0.18	0.18	1789	1789
encapsulation	organic material	carbon black	1333-86-4	8.853	0.58		5780	
	plastics	epoxy resin	-	97.384	6.36		63580	
leadfinish	inorganic material	silicondioxide	60676-86-0	483.970	31.60	38.54	315974	385334
	non noble metal	tin	7440-31-5	13.037	0.85	0.85	8511	8511
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.212	0.01	0.01	139	140
solder	non noble metal	tin	7440-31-5	0.061	0.00		40	
	noble metal	silver	7440-22-4	0.076	0.00		50	
glue	non noble metal	lead	7439-92-1	2.921	0.19	0.19	1907	1997
	plastics	Polyimide	26023-21-2	0.338	0.02	0.02	220	220
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	iron	7439-89-6	0.106	0.01		69	
*deviation	non noble metal	copper	7440-50-8	106.210	6.93	6.94	69342	69432
	< 10%				Sum in total:		100.00	1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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